

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. – 19. (cancelled)
20. (Previously Presented) A curable adhesive composition for anchoring materials in or to concrete or masonry comprising: an epoxy resin comprising at least one polymerizable epoxy compound; and a curing agent consisting essentially of a plurality of aliphatic amines and at least one tertiary amine, wherein said adhesive composition has an epoxy:amine weight ratio of about 0.5:1 to about 10:1.
21. (Previously Presented) The curable adhesive composition of claim 20 wherein said plurality of aliphatic amines include a first aliphatic amine having an amine value of about 400 mg KOH/g to about 500 mg KOH/g and a second aliphatic amine having an amine value greater than about 550 mg KOH/g.
22. (Previously Presented) The curable adhesive composition of claim 21 wherein said second aliphatic amine has an amine value of about 550 mg KOH/g to about 700 mg KOH/g.
23. (Previously Presented) The curable adhesive composition of claim 22 wherein said first and second aliphatic amines have a glass transition temperature of about 130° F to about 135° F.
24. (Previously Presented) The curable composition of claim 20 wherein said aliphatic amines and said one or more tertiary amines are respectively present in a weight of about 15:1 to about 25:1.
25. (Currently Amended) The curable adhesive composition of claim 20 wherein said amine curing agent is present in an amount of about 5 to about 50 weight percent.

26. (Currently Amended) The curable adhesive composition of claim 20 wherein said amine curing agent is present in an amount of about 20 parts by weight of active components (pbwa) to about 50 pbwa.
27. (Currently Amended) The curable adhesive composition of claim 20 wherein said amine curing agent consists of said plurality of aliphatic amines and said at least one tertiary amine.
28. (Previously Presented) The curable adhesive composition of claim 20 wherein said polymerizable epoxy compound is derived from the reaction of difunctional bisphenol-A and epichlorohydrin.
29. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound has an epoxide equivalent weight of from about 180 to about 190.
30. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound is present in the adhesive composition in an amount of about 20 weight percent to about 40 weight percent.
31. (Previously Presented) The curable adhesive composition of claim 28 wherein said polymerizable epoxy compound is present in the adhesive compositions in an amount of about 70 parts by weight of active components (pbwa) to about 95 pbwa.
32. (Previously Presented) The adhesive composition of claim 20 wherein said epoxy resin further comprises a reactive diluent for said polymerizable epoxy compound.
33. (Previously Presented) The adhesive composition of claim 32 wherein said epoxy resin has an epoxy:reactive diluent weight ratio is from about 65:10 to about 90:0.5.

34. (Previously Presented) The adhesive composition of claim 32 wherein said epoxy resin comprises about 97 weight percent of said polymerizable epoxy compound and about 3 weight percent of said reactive diluent.
35. (Previously Presented) The adhesive composition of claim 32 wherein said reactive diluent is 1,4-cyclohexan-dimethanol diglycidyl ether.
36. (Previously Presented) The curable adhesive composition of claim 20 wherein said epoxy compound and said curing agent are present in amounts effective to produce an adhesive composition which passes ICBO Heat Creep Test (ICBO acceptance criteria AC58) at 110°F and which passes the ICBO Damp Hole Test at 75°F.
37. (Previously Presented) The adhesive composition of claim 20 having a cure time of no greater than about 2.5 hours.